STEAM Education and the Innovative Pedagogies in the Intelligence Era

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Message from the Guest Editors

As we enter the era of intelligence, emerging technologies such as Artificial Intelligence (AI) and Internet of Things (IoT), machine learning, Augmented Reality (AR), Virtual Reality (VR), Mixed Reality (MR), intelligent computing, blockchain, open-source hardware, 3D printing, etc., have provided significant enlightenment to education, and empower transformative teaching for STEM/STEAM.

This Special Issue seeks excellent original research articles, including empirical study and reviews, that are related to STEAM education and the innovative pedagogies in the intelligence era. Topics of primary interest include but are not limited to:

- Innovative design of pedagogical content in STEAM
- Innovative practice approaches of STEAM
- Innovative evaluation of STEAM
- Intelligent environment of STEAM
- Innovative online/mixed STEAM
- Artificial Intelligence (AI) and STEAM
- STEAM education and creativity.
- STEAM education and culture in the intelligence era.
- STEAM education and educational equality in the intelligence era.
- STEAM education towards the cultivation of future talents.
- Security, trust, and collaboration in STEAM

Special Issue

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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